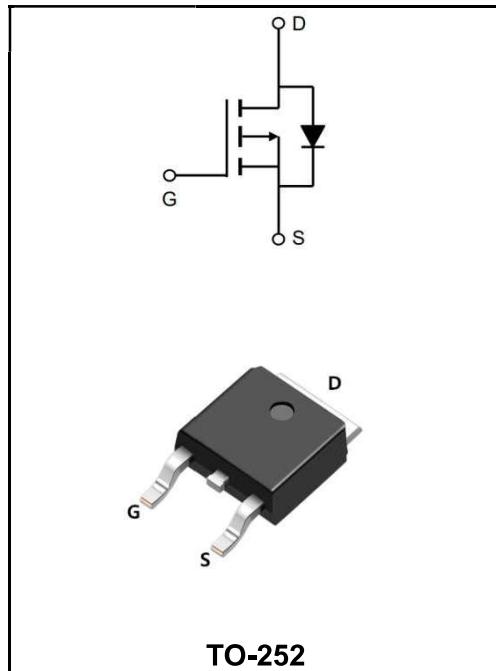


**-40V P-CHANNEL ENHANCEMENT MODE MOSFET**
**MAIN CHARACTERISTICS**

$I_D$	-15A
$V_{DSS}$	-40V
$R_{DS(on)-typ}(@V_{GS}=-10V)$	< 32mΩ (Type: 27 mΩ)


**Application**

- ◆ Battery protection
- ◆ Load switch
- ◆ Uninterruptible power supply

**Product Specification Classification**

Part Number	Package	Marking	Pack
YFW15P04AD	TO-252	YFW 15P04AD XXXXX	2500PCS/Tape

**Maximum Ratings at  $T_c=25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbols	Value	Units
Drain-Source Voltage	$V_{DS}$	-40	V
Gate - Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current, $V_{GS} @ -10V^1$ @ $T_c=25^\circ\text{C}$	$I_D$	-15	A
Continuous Drain Current, $V_{GS} @ -10V^1$ @ $T_c=100^\circ\text{C}$	$I_D$	-11	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	-54	A
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	40.9	mJ
Avalanche Current	$I_{AS}$	-28.6	A
Total Power Dissipation <sup>4</sup> @ $T_c=25^\circ\text{C}$	$P_D$	35	W
Storage Temperature Range	$T_{STG}$	-55 to +150	°C
Operating Junction Temperature Range	$T_J$	-55 to +150	°C
Thermal Resistance Junction-Ambient <sup>1</sup>	$R_{\theta JA}$	62	°C/W
Thermal Resistance Junction to Case <sup>1</sup>	$R_{\theta JC}$	3.8	°C/W

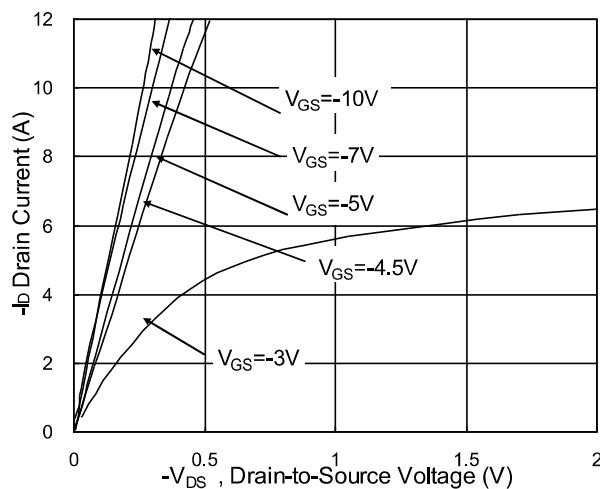
**Maximum Ratings at T<sub>c</sub>=25°C unless otherwise specified**

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	BV <sub>DSS</sub>	-40	-47	-	V
BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =-1mA	ΔBV <sub>DSS/ΔTJ</sub>	-	-0.02	-	V/°C
Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-8A	R <sub>DS(ON)</sub>	-	27	32	mΩ
	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4A		-	39	46	
Gate -Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250uA	V <sub>GS(th)</sub>	-1.0	-1.6	-2.5	V
V <sub>GS(th)</sub> Temperature Coefficient		ΔV <sub>GS(th)</sub>	-	3.72	-	mV/°C
Drain-Source Leakage Current	V <sub>DS</sub> =-32V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	I <sub>DSS</sub>	-	-	1	μA
	V <sub>DS</sub> =-32V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C		-	-	5	
Gate –Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	I <sub>GSS</sub>	-	-	±100	nA
Forward Transconductance	V <sub>DS</sub> =-5V , I <sub>D</sub> =-8A	g <sub>fs</sub>	-	10.7	-	S
Total Gate Charge(-4.5V)	V <sub>DS</sub> =-15V V <sub>GS</sub> =-4.5V I <sub>D</sub> =-1A	Q <sub>g</sub>	-	11.5	-	nC
Gate-Source Charge		Q <sub>gs</sub>	-	3.5	-	
Gate-Drain Charge		Q <sub>gd</sub>	-	3.3	-	
Turn-on delay time	V <sub>DD</sub> =-15V V <sub>GS</sub> =-10V I <sub>D</sub> = -1A R <sub>G</sub> =3.3Ω	t <sub>d(on)</sub>	-	22	-	ns
Rise Time		T <sub>r</sub>	-	15.7	-	
Turn-Off Delay Time		t <sub>d(OFF)</sub>	-	59	-	
Fall Time		t <sub>f</sub>	-	5.5	-	
Input Capacitance	V <sub>DS</sub> =-15V V <sub>GS</sub> =0V f=1MHz	C <sub>iss</sub>	-	415	-	pF
Output Capacitance		C <sub>oss</sub>	-	134	-	
Reverse Transfer Capacitance		C <sub>rss</sub>	-	102	-	
Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	I <sub>s</sub>	-	-	-27	A
Pulsed Source Current <sup>2,5</sup>		I <sub>SM</sub>	-	-	-54	A
Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25°C	V <sub>SD</sub>	-	-	-1.2	V

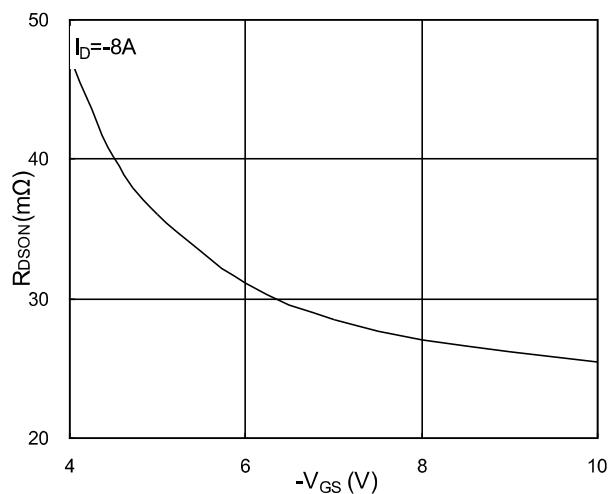
Note :

1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
3. The EAS data shows Max. rating . The test condition is V DD =-25V,V GS =-10V,L=0.1mH,I AS =-28.6A
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation

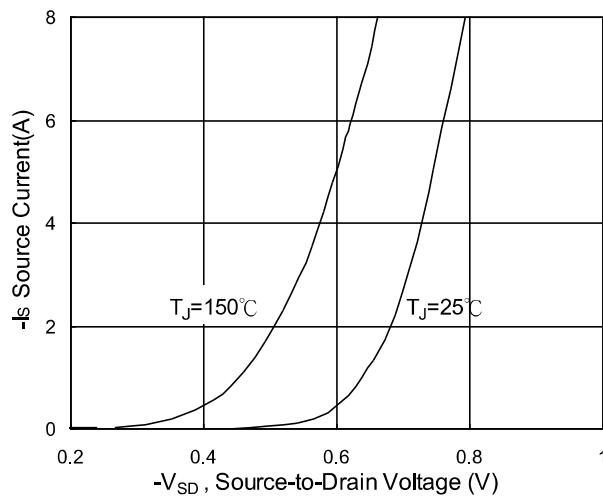
**Ratings and Characteristic Curves**



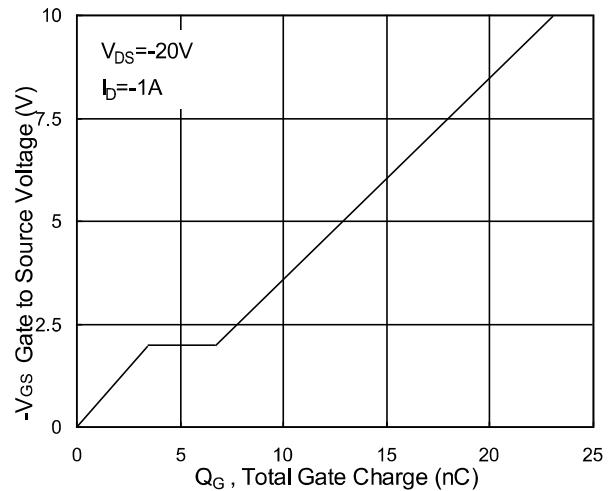
**Fig.1 Typical Output Characteristics**



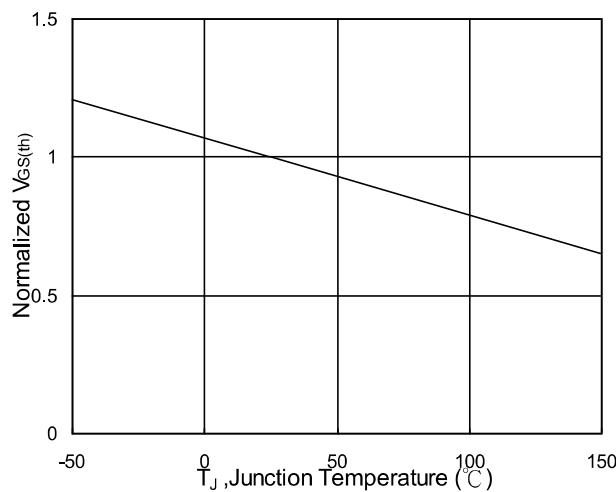
**Fig.2 On-Resistance v.s Gate-Source**



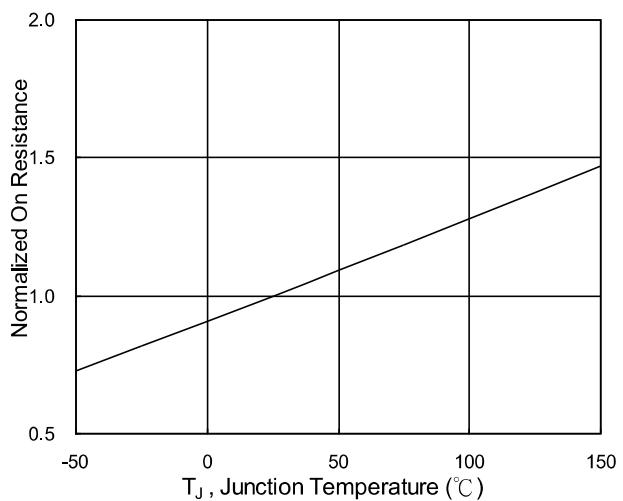
**Fig.3 Forward Characteristics Of Reverse**



**Fig.4 Gate Charge Characteristics**

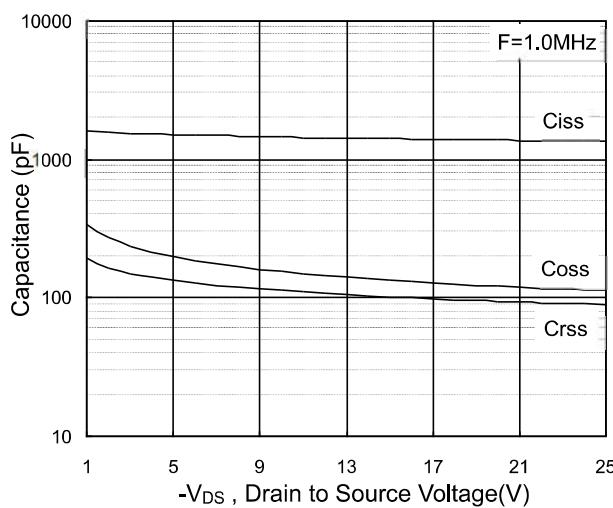


**Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$**

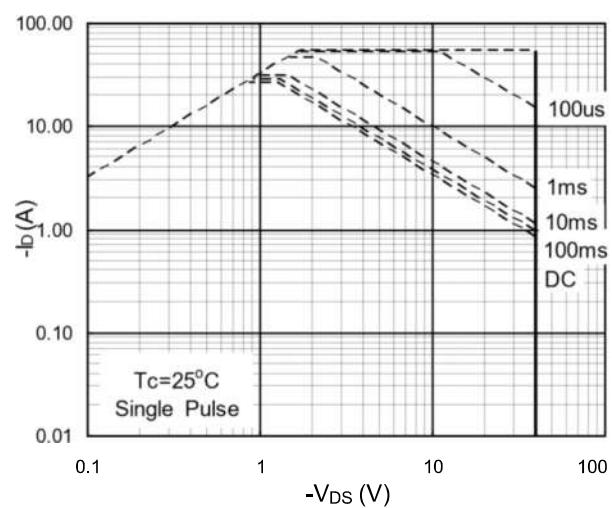


**Fig.6 Normalized  $R_{DSON}$  v.s  $T_J$**

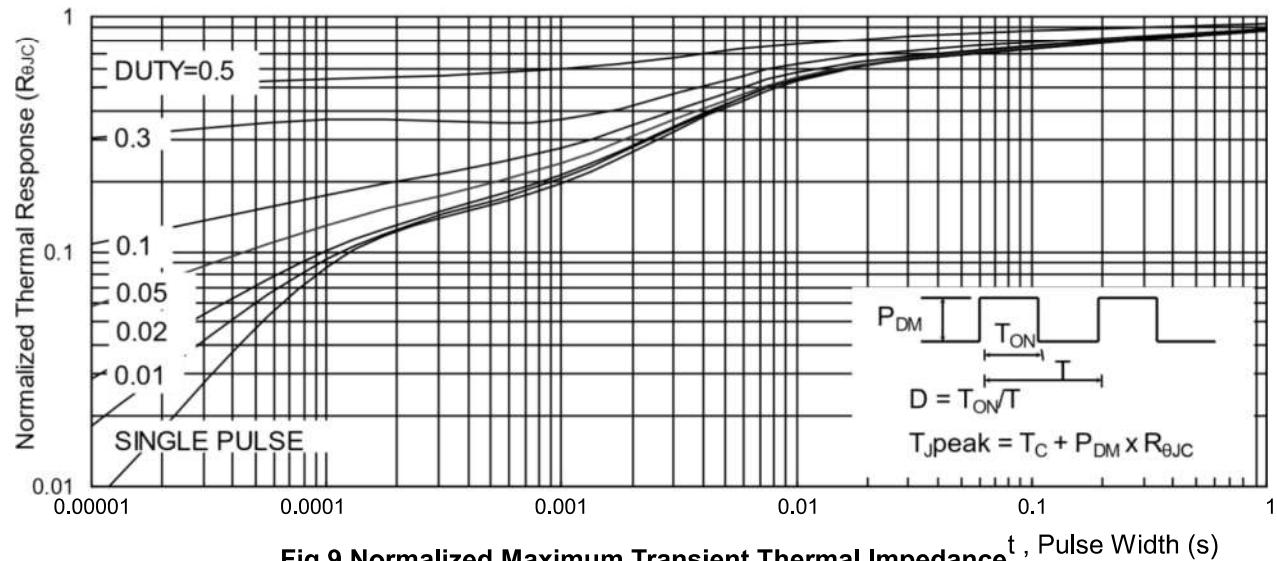
**Ratings and Characteristic Curves**



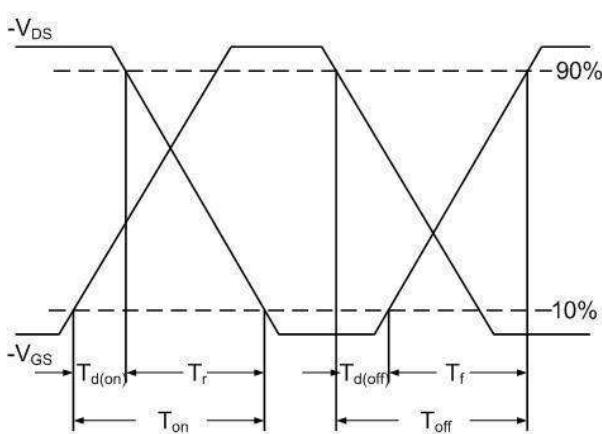
**Fig.7 Capacitance**



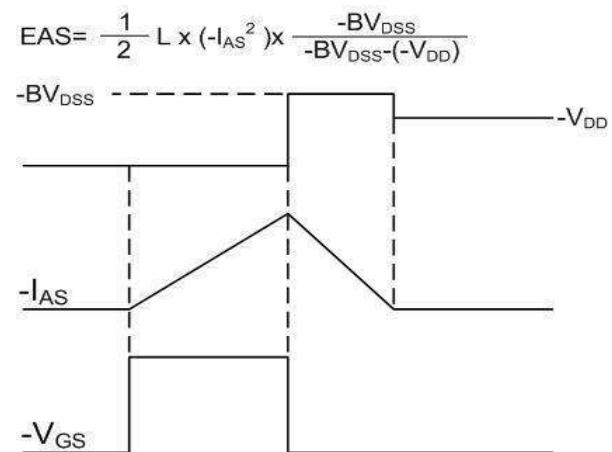
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Waveform**

**Package Outline Dimensions Millimeters**

**TO-252**

Dim.	Min.	Typ.	Max.
A	2.10	-	2.50
A2	0	-	0.10
B	0.66	-	0.86
B2	5.18	-	5.48
C	0.40	-	0.60
C2	0.44	-	0.58
D	5.90	-	6.30
D1	5.30REF		
E	6.40	-	6.80
E1	4.63	-	-
G	4.47	-	4.67
H	9.50	-	10.70
L	1.09	-	1.21
L2	1.35	-	1.65
V1	-	7°	-
V2	0°	-	6°

All Dimensions in millimeter